TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $L^2$ - $\pi$ -MOSV)

# 2SK2266

# Chopper Regulator, DC–DC Converter and Motor Drive Applications

• 4-V gate drive

• Low drain–source ON resistance : RDS (ON) = 22 m $\Omega$  (typ.)

• High forward transfer admittance  $: |Y_{fs}| = 27 \text{ S (typ.)}$ • Low leakage current  $: I_{DSS} = 100 \,\mu\text{A (max) (V}_{DS} = 60 \,\text{V)}$ 

• Enhancement mode  $: V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$ 

#### Absolute Maximum Ratings (Ta = 25°C)

| Characteristics                              |                | Symbol           | Rating  | Unit |  |
|--|----------------|------------------|---------|------|--|
| Drain-source voltage                         |                | $V_{DSS}$        | 60      | V    |  |
| Drain-gate voltage (R <sub>GS</sub> = 20 kΩ) |                | $V_{DGR}$        | 60      | V    |  |
| Gate-source voltage                          |                | $V_{GSS}$        | ±20     | V    |  |
| Drain current                                | DC (Note 1)    | $I_{D}$          | 45      | А    |  |
|  | Pulse (Note 1) | $I_{DP}$         | 180     |      |  |
| Drain power dissipation (Tc = 25°C)          |                | $P_{D}$          | 65      | W    |  |
| Single pulse avalanche energy (Note 2)       |                | E <sub>AS</sub>  | 246     | mJ   |  |
| Avalanche current                            |                | I <sub>AR</sub>  | 45      | Α    |  |
| Repetitive avalanche energy (Note 3)         |                | E <sub>AR</sub>  | 6.5     | mJ   |  |
| Channel temperature                          |                | T <sub>ch</sub>  | 150     | °C   |  |
| Storage temperature range                    |                | T <sub>stg</sub> | -55~150 | °C   |  |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

| Characteristics                        | Symbol                 | Max  | Unit |
|--|------------------------|------|------|
| Thermal resistance, channel to case    | R <sub>th (ch-c)</sub> | 1.92 | °C/W |
| Thermal resistance, channel to ambient | R <sub>th (ch-a)</sub> | 83.3 | °C/W |

Note 1: Ensure that the channel temperature does not exceed 150°C.

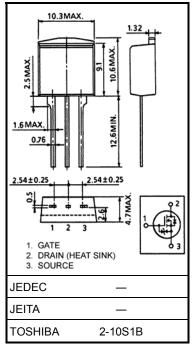
Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 165  $\mu$ H, RG = 25  $\Omega$ ,  $I_{AR}$  = 45 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

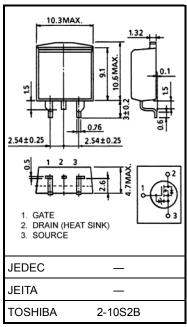
This transistor is an electrostatic-sensitive device.

Please handle with caution.

Unit: mm



Weight: 1.5 g (typ.)



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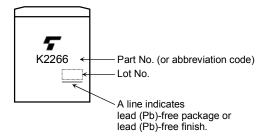
## **Electrical Characteristics (Ta = 25°C)**

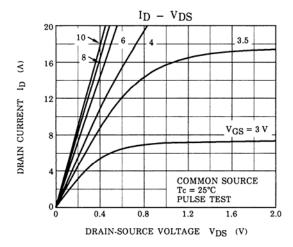
| Charac  | eteristics           | Symbol  | Test Condition   | Min | Тур. | Max | Unit  |
|---|----------------------|---|--|-----|------|-----|-------|
| Gate leakage cu                                 | ırrent               | I <sub>GSS</sub>                              | V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V   | _   | _    | ±10 | μΑ    |
| Drain cut-off cu                                | rrent                | I <sub>DSS</sub>                              | V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V  | _   | _    | 100 | μA    |
| Drain–source br<br>voltage                      | eakdown              | V (BR) DSS                                    | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V  | 60  | _    | _   | V     |
| Gate threshold v                                | oltage               | $V_{th}$                                      | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA  | 8.0 | _    | 2.0 | V     |
| Drain course O                                  | N resistance         | Б   | V <sub>GS</sub> = 4 V, I <sub>D</sub> = 15 A   | _   | 40   | 55  |       |
| Drain–source ON resistance                      | R <sub>DS (ON)</sub> | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 25 A | _  | 22  | 30   | mΩ  |       |
| Forward transfer                                | r admittance         | Y <sub>fs</sub>                               | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 25 A  | 15  | 27   | _   | S     |
| Input capacitano                                | e                    | C <sub>iss</sub>                              |  | _   | 1800 | _   |       |
| Reverse transfer capacitance                    |                      | C <sub>rss</sub>                              | V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz   | _   | 350  | _   | pF    |
| Output capacitance                              |                      | Coss  |  |     | 900  | _   |       |
| Switching time                                  | Rise time            | t <sub>r</sub>                                | $V_{GS} \stackrel{10V}{\underset{OV}{\downarrow}} \stackrel{I_{D}=25A}{\underset{R_{L}}{\downarrow}} V_{OUT}$ $V_{DD} = 30V$ |     | 20   | ı   |       |
|   | Turn-on time         | t <sub>on</sub>                               |  |     | 30   | -   | ns    |
|   | Fall time            | t <sub>f</sub>                                |  |     | 40   | -   | . 115 |
|   | Turn-off time        | t <sub>off</sub>                              | Duty $\leq 1\%$ , $t_{\mathbf{W}} = 10 \mu \text{s}$   | _   | 130  | _   |       |
| Total gate charge (Gate–source plus gate–drain) |                      | Qg  |  | _   | 60   | _   |       |
| Gate-source charge                              |                      | Q <sub>gs</sub>                               | $V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 45 \text{ A}$   | _   | 40   | _   | nC    |
| Gate-drain ("miller") charge                    |                      | Q <sub>gd</sub>                               |  |     | 20   | _   |       |

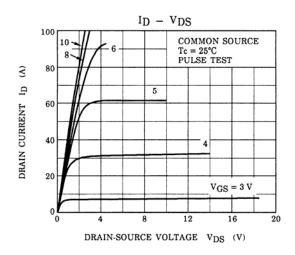
## Source-Drain Ratings and Characteristics (Ta = 25°C)

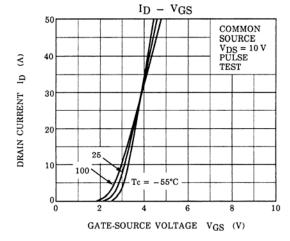
| Characteristics                           | Symbol           | Test Condition   | Min | Тур. | Max  | Unit |
|---|------------------|--|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I <sub>DR</sub>  | _  | 1   | _    | 45   | Α    |
| Pulse drain reverse current (Note 1)      | I <sub>DRP</sub> | _  |     | _    | 180  | Α    |
| Forward voltage (diode)                   | V <sub>DSF</sub> | I <sub>DR</sub> = 45 A, V <sub>GS</sub> = 0 V                                    | _   | _    | -1.8 | V    |
| Reverse recovery time                     | t <sub>rr</sub>  | I <sub>DR</sub> = 45 A, V <sub>GS</sub> = 0 V, dI <sub>DR</sub> / dt = 50 A / μs | _   | 90   | _    | ns   |
| Reverse recovery charge                   | Q <sub>rr</sub>  |  | -   | 0.1  | _    | μC   |

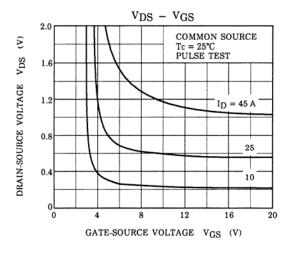
## Marking

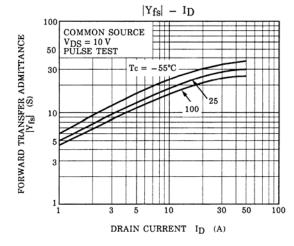


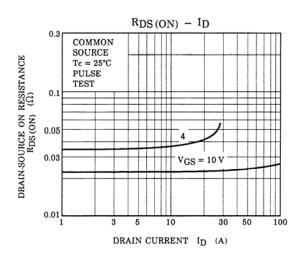


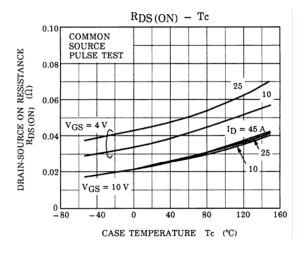


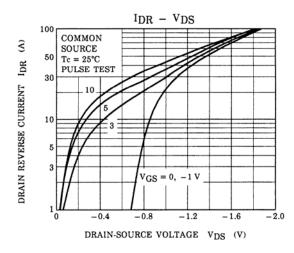


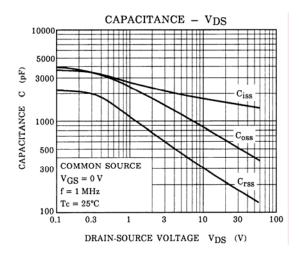


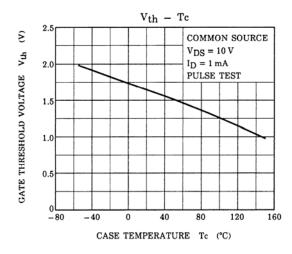


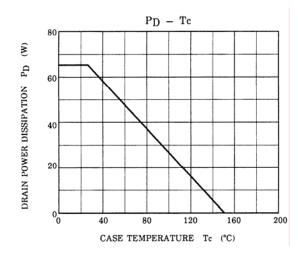


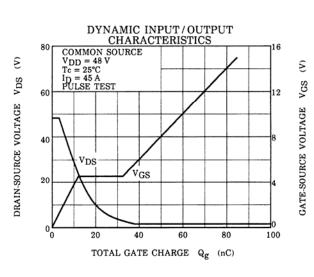




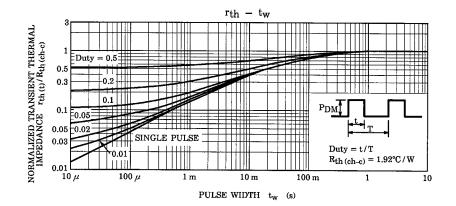


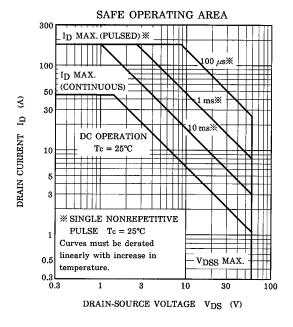


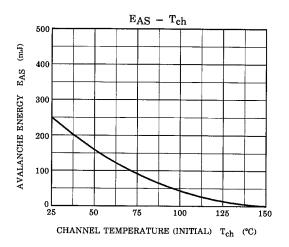


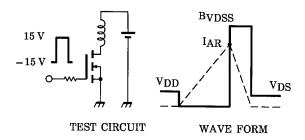


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$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 25~V,~L = 165~\mu H \end{aligned} \qquad EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right)$$

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